High Voltage LED Series
Chip on Board

LC006D – Gen.1

High efficacy COB LED package
well-suited for use in spotlight applications

Features & Benefits

- Chip on Board (COB) solution makes it easy to design in
- Simple assembly reduces manufacturing cost
- Low thermal resistance
- InGaN/GaN MQW LED with long time reliability

Applications

- Spotlight / Downlight
- LED Retrofit Bulbs
- Outdoor Illumination

SAMSUNG

Table of Contents

1. Characteristics

a) Absolute Maximum Rating

Item	Symbol	Rating	Unit	Condition
Ambient / Operating Temperature	T_a	-40 ~ +105	ºC	-
Storage Temperature	T_{stg}	-40 ~ +120	ºC	-
LED Junction Temperature	T_J	140	ºC	-
Case Temperature	Tc	105	ºC	
Forward Current	I_F	460	mA	-
Power Dissipation	P_D	17.2	W	-
ESD (HBM)	-	±2	kV	-
ESD (MM)	-	±0.5	kV	-

b) Electro-optical Characteristics (I_F = 180 mA, T_J = 85 ºC)

Item	Unit	Rank	Min.	Typ.	Max.
Forward Voltage (V_F)	V	YZ	31.8	34.6	37.5
Color Rendering Index (R_a)	-	5	80	-	-
		7	90		
Thermal Resistance (junction to chip point)	ºC/W		-	2.4	-
Beam Angle	º		-	115	-
Nominal Power	W			6.4	

Notes:

1) The COB is tested in pulsed condition at rated test current (10 ms pulse width) and rated temperature (T_J = T_C = T_a = 85 °C)
2) Samsung maintains measurement tolerance of: forward voltage = ±5 %, CRI = ±1
3) Refer to the derating curve, '3. Typical Characteristics Graph' designed within the range.

c) Luminous Flux Characteristics (I_F = 180 mA)

CRI (R_a) Min.	Nominal CCT (K)	Flux Rank	Flux @ T_J = 85 °C (lm)		
			Min.	Typ.	Max.
80	2700	E9	791	832	-
		D1	832	874	-
	3000	F3	831	875	-
		D1	875	919	-
	3500	F5	857	902	-
		D1	902	947	-
	4000	F8	877	923	-
		D1	923	969	-
	5000	F8	882	928	-
		D1	928	975	-
	5700	F8	882	928	-
		D1	928	975	-
	6500	F8	872	918	-
		D1	918	964	-

CRI (R_a) Min.	Nominal CCT (K)	Flux Rank	Flux @ T_J = 85 °C (lm)		
			Min.	Typ.	Max.
90	2700	D7	673	709	-
		D1	709	744	-
	3000	E9	706	743	-
		D1	743	780	-
	3500	E0	730	768	-
		D1	768	807	-
	4000	E4	745	784	-
		D1	784	824	-
	5000	E4	748	787	-
		D1	787	827	-

Notes:

1) The COB is tested in pulsed operating condition at rated test current (10 ms pulse width) and rated temperature (T_j = T_c = 85 °C).
2) Samsung maintains measurement tolerance of: Luminous flux = ±7 %, CRI = ±1

2. Product Code Information

1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18
S	P	H	W	H	A	H	D	N	B	2	5	Y	Z	W	3	E	9

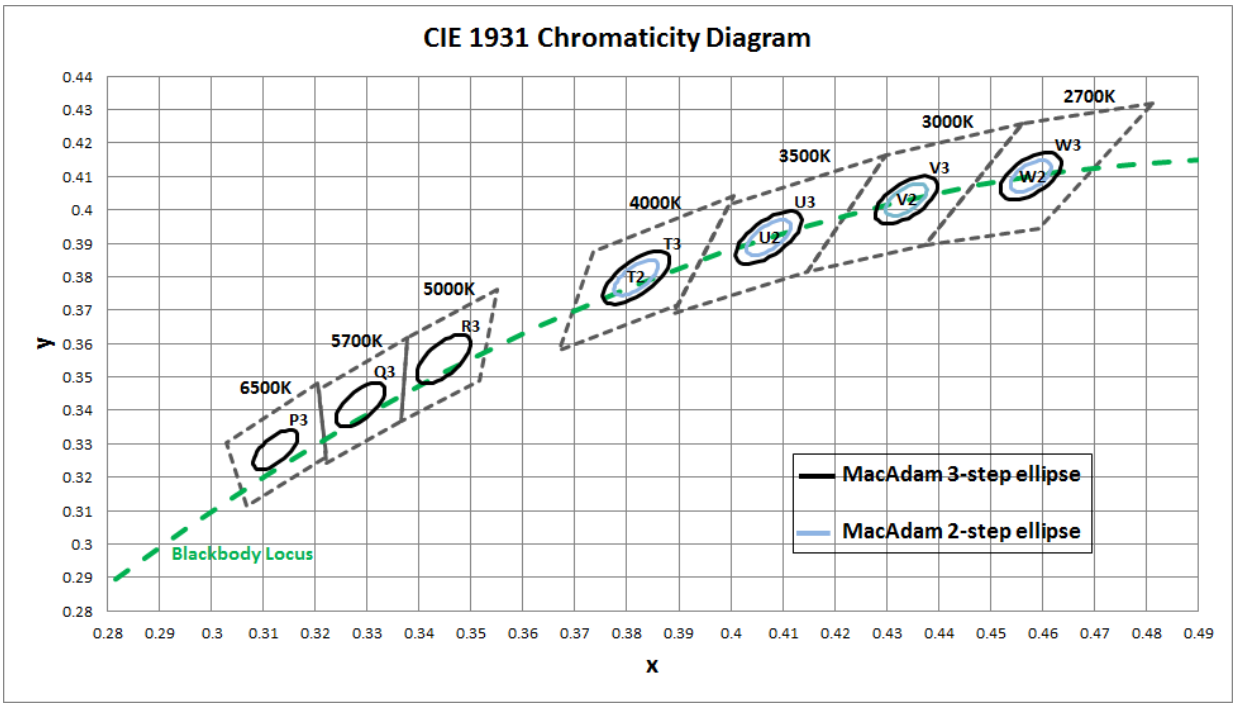
Digit	PKG Information	Code	Specification
1 2 3	Samsung Package High Power	SPH	
4 5	Color	WH	White
6	Product Version	A	
7 8	Form Factor	HD	COB
9	Lens Type	N	No lens
10	Wattage or Model	B	LC006D
11	Internal Code	2	
12	CRI & Sorting Temperature	5	Min. 80 (85℃)
		7	Min. 90 (85℃)
13 14	Forward Voltage (V)	YZ	31.8~37.5
15	CCT (K)	W	2700K
		V	3000K
		U	3500K
		T	4000K
		R	5000K
		Q	5700K
		P	6500K
16	MacAdam Step	2	MacAdam 2-step
		3	MacAdam 3-step
17 18	Luminous Flux (Lm)	D7	Min. 670
		E0	Min. 700
		E4	Min. 740
		E9	Min. 790
		F3	Min. 830
		F5	Min. 850
		F7	Min. 870
		F8	Min. 880
		D1	Add Rank

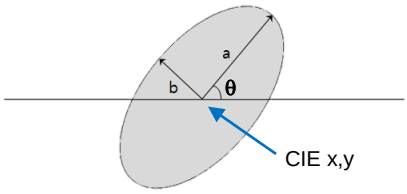
a) Binning Structure (I_F = 180 mA, T_J = 85 ºC)

CRI (R_a) Min.	Nominal CCT (K)	Product Code	V_F Rank	Color Rank	Flux Rank	Flux Range (Φ_v, lm)
80	2700	SPHWHAHDNB25YZW2E9	YZ	W2	E9	791 ~
		SPHWHAHDNB25YZW3E9		W3		
		SPHWHAHDNB25YZW2D1		W2	D1	832 ~
		SPHWHAHDNB25YZW3D1		W3		
	3000	SPHWHAHDNB25YZV2F3	YZ	V2	F3	831 ~
		SPHWHAHDNB25YZV3F3		V3		
		SPHWHAHDNB25YZV2D1		V2	D1	875 ~
		SPHWHAHDNB25YZV3D1		V3		
	3500	SPHWHAHDNB25YZU2F5	YZ	U2	F5	857 ~
		SPHWHAHDNB25YZU3F5		U3		
		SPHWHAHDNB25YZU2D1		U2	D1	902 ~
		SPHWHAHDNB25YZU3D1		U3		
	4000	SPHWHAHDNB25YZT2F8	YZ	T2	F8	877 ~
		SPHWHAHDNB25YZT3F8		T3		
		SPHWHAHDNB25YZT2D1		T2	D1	923 ~
		SPHWHAHDNB25YZT3D1		T3		
	5000	SPHWHAHDNB25YZR3F8	YZ	R2	F8	882 ~
		SPHWHAHDNB25YZR3D1		R3	D1	928 ~
	5700	SPHWHAHDNB25YZQ3F8	YZ	Q2	F8	882 ~
		SPHWHAHDNB25YZQ3D1		Q3	D1	928 ~
	6500	SPHWHAHDNB25YZP3F7	YZ	P2	F7	872 ~
		SPHWHAHDNB25YZP3D1		P3	D1	918 ~

CRI (R_a) Min.	Nominal CCT (K)	Product Code	V_F Rank	Color Rank	Flux Rank	Flux Range (Φ_v, lm)
90	2700	SPHWHAHDNB27YZW2D7	YZ	W2	D7	673 ~
		SPHWHAHDNB27YZW3D7		W3		
		SPHWHAHDNB27YZW2D1		W2	D1	709 ~
		SPHWHAHDNB27YZW3D1		W3		
	3000	SPHWHAHDNB27YZV2E9	YZ	V2	E9	706 ~
		SPHWHAHDNB27YZV3E9		V3		
		SPHWHAHDNB27YZV2D1		V2	D1	743 ~
		SPHWHAHDNB27YZV3D1		V3		
	3500	SPHWHAHDNB27YZU2E0	YZ	U2	E0	730 ~
		SPHWHAHDNB27YZU3E0		U3		
		SPHWHAHDNB27YZU2D1		U2	D1	768 ~
		SPHWHAHDNB27YZU3D1		U3		
	4000	SPHWHAHDNB27YZT2E4	YZ	T2	E4	745 ~
		SPHWHAHDNB27YZT3E4		T3		
		SPHWHAHDNB27YZT2D1		T2	D1	784 ~
		SPHWHAHDNB27YZT3D1		T3		
	5000	SPHWHAHDNB27YZR3E4	YZ	R3	E4	748 ~
		SPHWHAHDNB27YZR3D1		R3	D1	787 ~

b) Chromaticity Region & Coordinates (I_F = 180 mA, T_J = 85 °C)





MacAdam Ellipse (W2, W3)					
Step	CIE x	CIE y	θ	a	b
2-step	0.4578	0.4101	53.70	0.0054	0.0028
3-step	0.4578	0.4101	53.70	0.0081	0.0042

MacAdam Ellipse (V2, V3)					
Step	CIE x	CIE y	θ	a	b
2-step	0.4338	0.403	53.22	0.0056	0.0027
3-step	0.4338	0.4030	53.22	0.0083	0.0041

MacAdam Ellipse (U2, U3)					
Step	CIE x	CIE y	θ	a	b
2-step	0.4073	0.3917	54.00	0.0062	0.0028
3-step	0.4073	0.3917	54.00	0.0093	0.0041

MacAdam Ellipse (T2, T3)					
Step	CIE x	CIE y	θ	a	b
2-step	0.3818	0.3797	53.72	0.0063	0.0027
3-step	0.3818	0.3797	53.72	0.0094	0.0040

MacAdam Ellipse (R3)					
Step	CIE x	CIE y	θ	a	b
3-step	0.3447	0.3553	59.62	0.0082	0.0035

MacAdam Ellipse (Q3)					
Step	CIE x	CIE y	θ	a	b
3-step	0.3287	0.3417	59.0950	0.0075	0.0032

MacAdam Ellipse (P3)					
Step	CIE x	CIE y	θ	a	b
3-step	0.3123	0.3282	58.5700	0.0067	0.0029

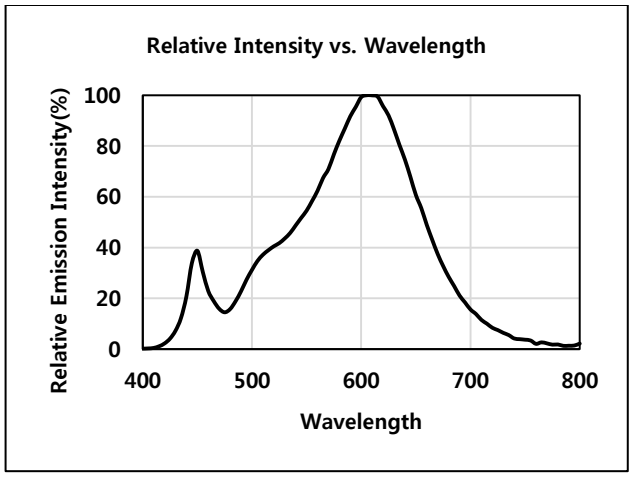
Note:

Samsung maintains measurement tolerance of: Cx, Cy = ±0.005

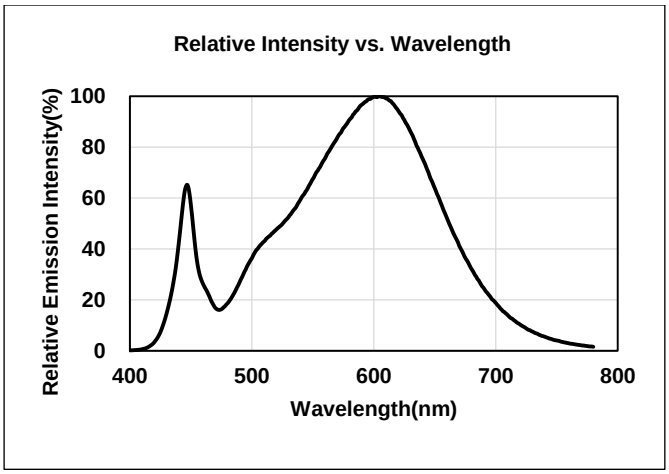
3. Typical Characteristics Graphs

b) Beam Angle Characteristics (I_F = 180 mA, T_J = 85 °C)

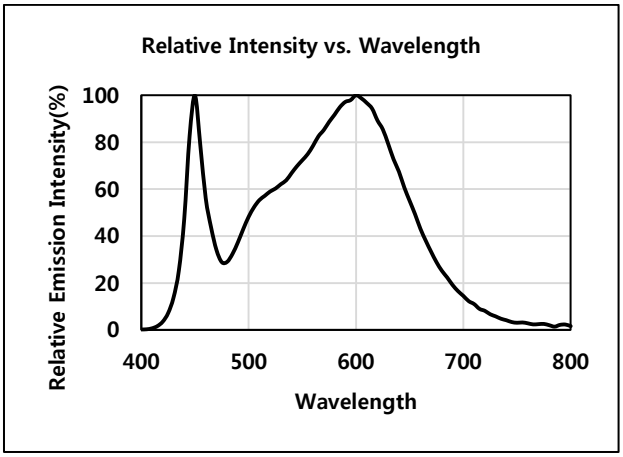
CCT: 2700 K (80 CRI)



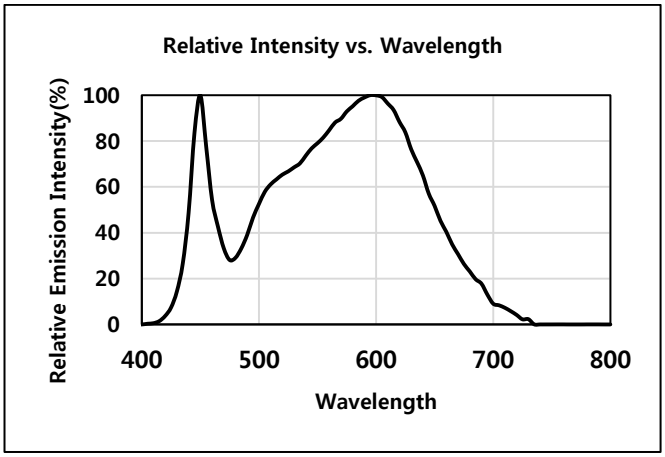
CCT: 3000 K (80 CRI)



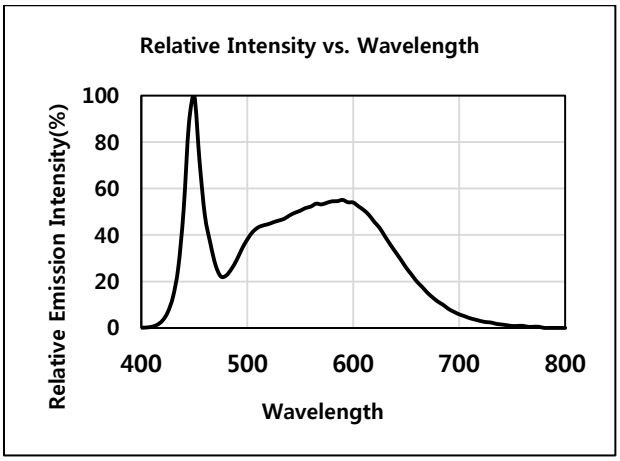
CCT: 3500 K (80 CRI)



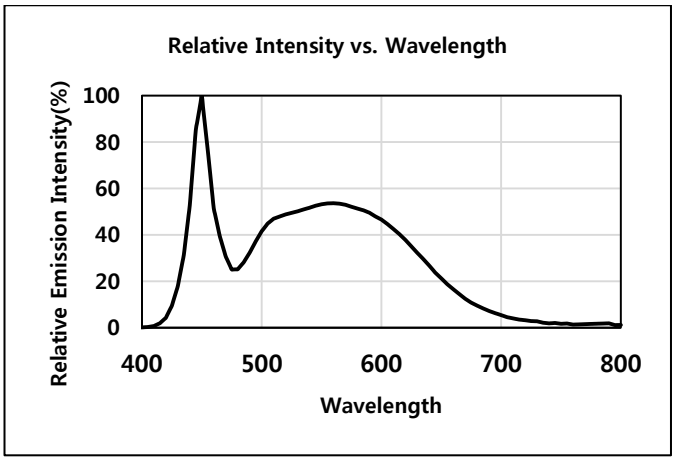
CCT: 4000 K (80 CRI)



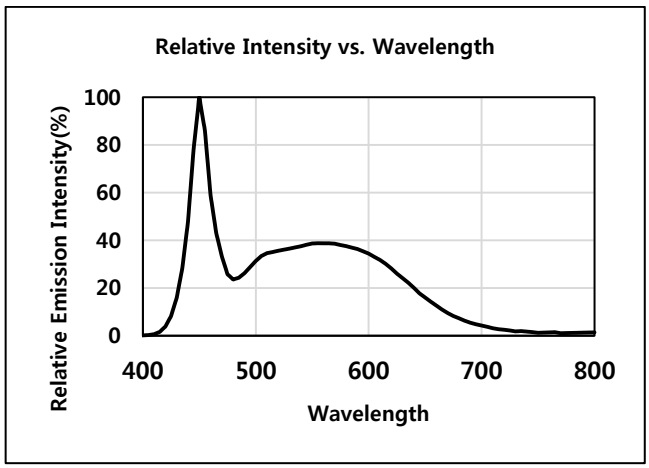
CCT: 5000 K (80 CRI)



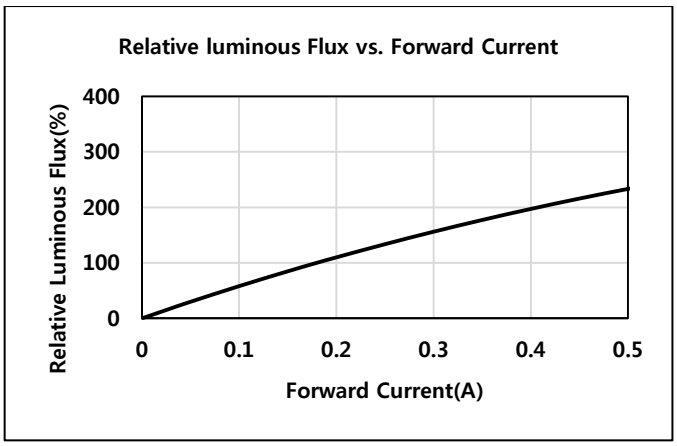
CCT: 5700 K (80 CRI)

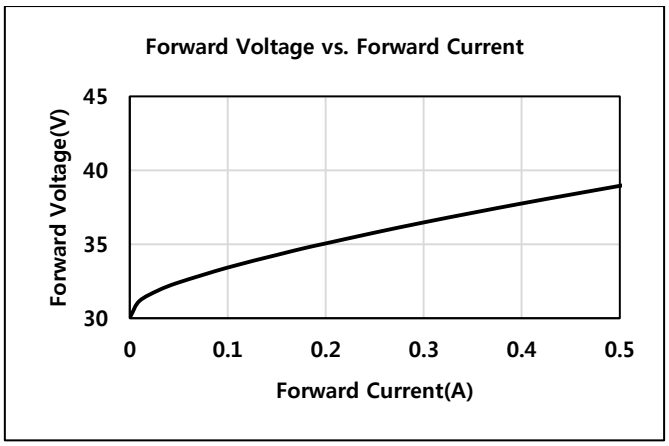


CCT: 6500 K (80 CRI)

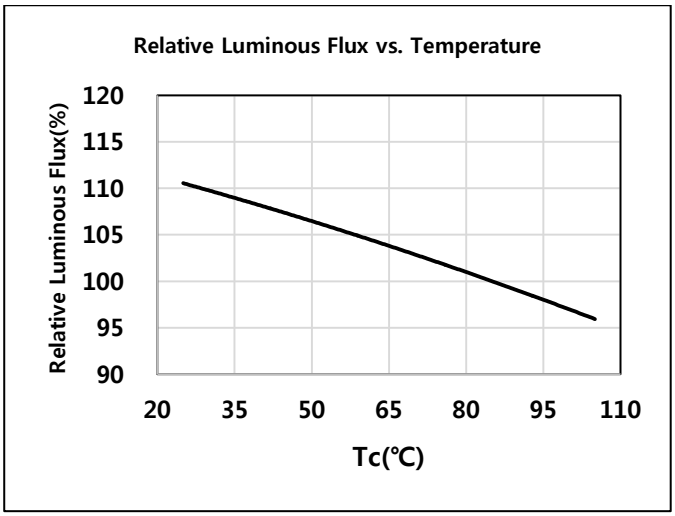


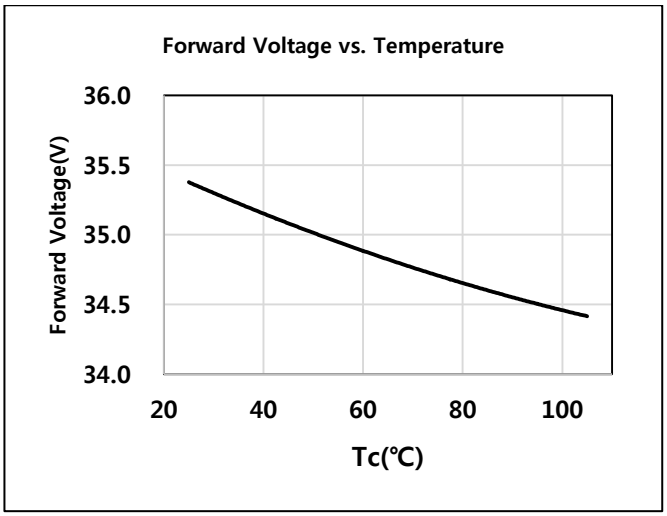
b) Forward Current Characteristics (T_J = 85 ºC)



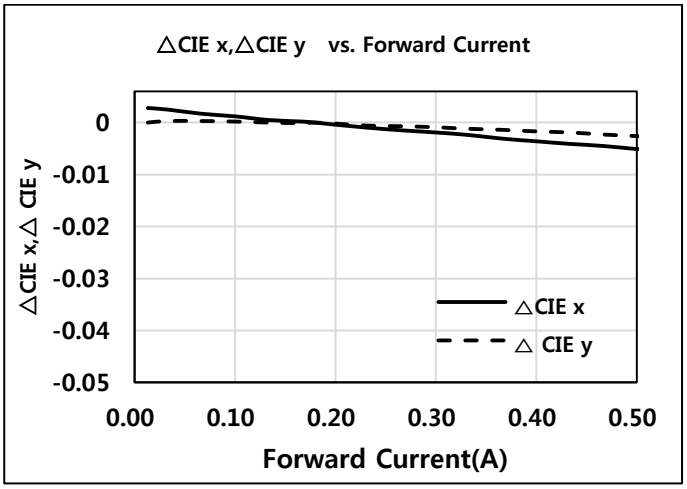


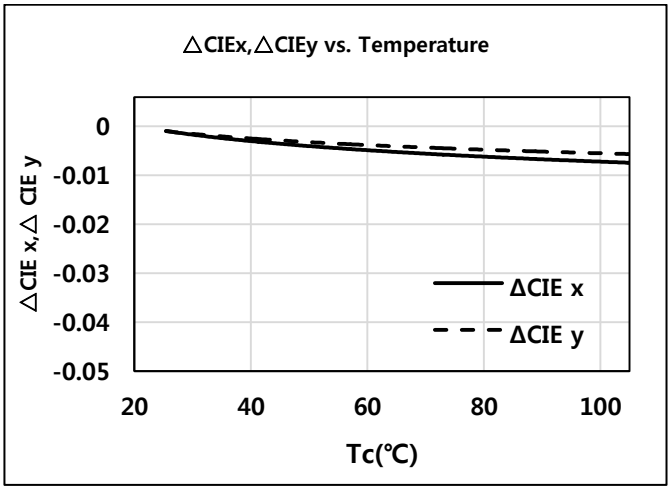
C) Temperature Characteristics (I_F = 180mA)



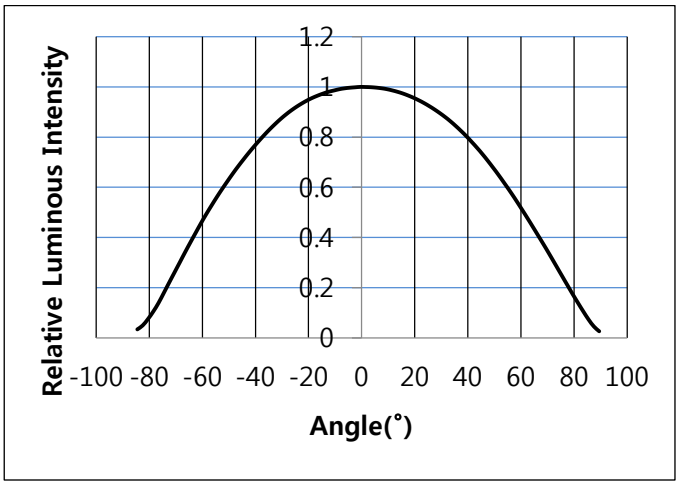


d) Color Shift Characteristics (T_J = 85 °C, CRI 80+)

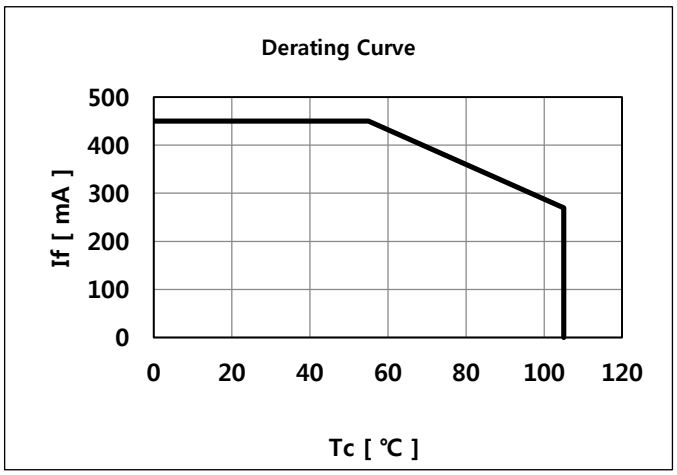




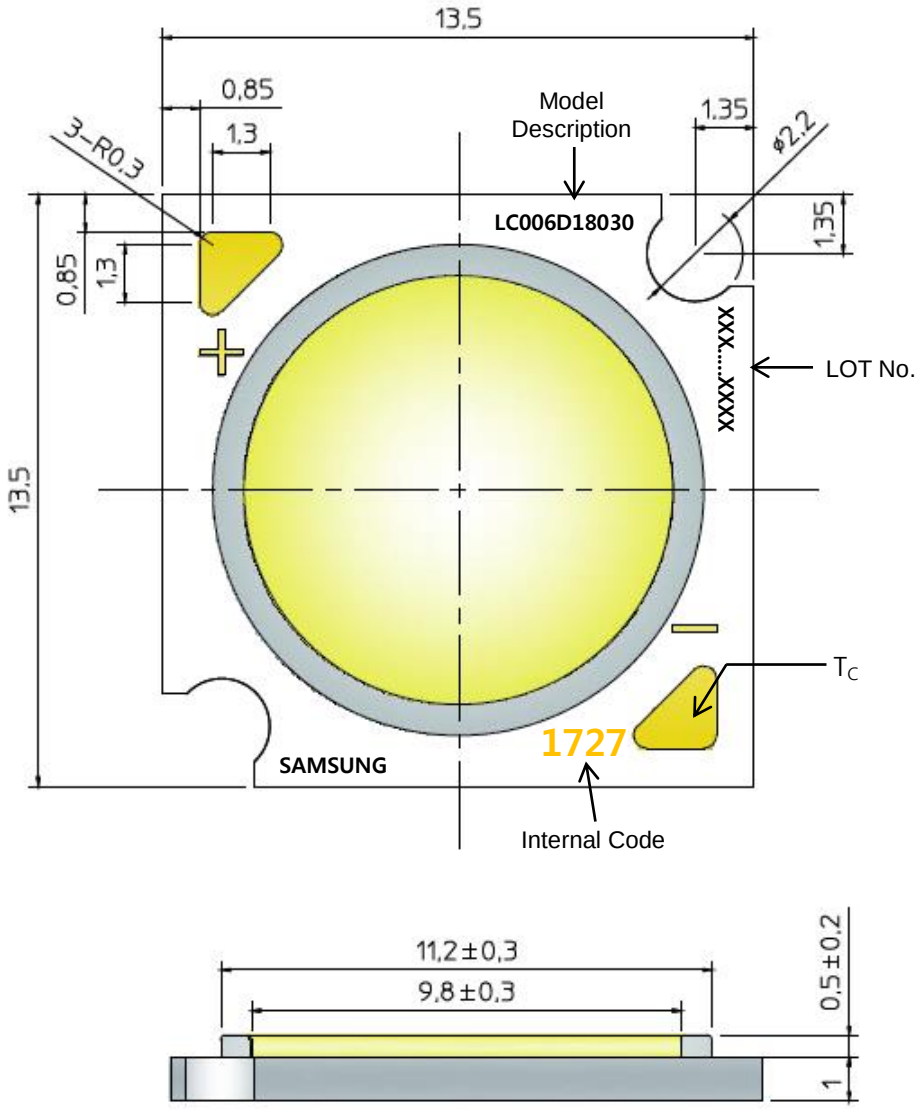
e) Beam Angle Characteristics (I_F = 180 mA, T_J = 85 °C)



f) Derating Characteristics



4. Outline Drawing & Dimension



1. Unit: mm
2. Tolerance: ± 0.30 mm

Item	Dimension	Tolerance	Unit
Length	13.5	±0.15	mm
Width	13.5	±0.15	mm
Height	1.50	±0.20	mm
Light Emitting Surface (LES) Diameter	9.8	±0.30	mm

Note: Denoted product information above is only an example
(LC006D18030 : LC006D, CRI80+, 3000K)

5. Reliability Test Items & Conditions

a) Test Items

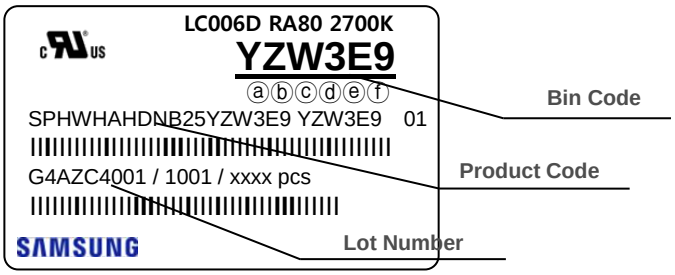
Test Item	Test Condition	Test Hour / Cycle
High Temperature Humidity Life Test	60 ºC, 90 % RH,, DC Derating, I_F	1000 h
High Temperature Life Test	85 ºC, DC Derating, I_F	1000 h
Low Temperature Life Test	-40 ºC, DC , I_F = 320 mA	1000 h
Pulsed Operating Life Test	55 ℃, Pulse width 100 μs, duty cycle 3 %	1000 h
High Temperature Storage	120 ºC	1000 h
Low Temperature Storage	-40 ºC	1000 h
Temperature Humidity Storage	60 ºC, 90% RH	1000h
Temperature Cycle On/Off Test	-40 ºC / 85 ºC each 20 min, 30 min transfer power on/off each 5 min, DC Derating, I_F = max	100 cycles
ESD (HBM)	R_1: 10 MΩ R_2: 1.5 kΩ C: 100 pF V: ±2 kV	5 times
ESD (MM)	R_1: 10 MΩ R_2: 0 kΩ C: 200 pF V: ±0.2 kV	5 times
Vibration Test	20 ~ 80 Hz (displacement: 0.06 inch, max. 20 g) 80 ~ 2 kHz (max. 20 g) min. frequency ↔ max. frequency 4 min transfer	4 times
Mechanical Shock Test	1500 g, 0.5 ms each of the 6 surfaces (3 axis x 2 sides)	5 times
Sulfur Resistance	25 °C, 75%, H2S 15 ppm	504h

b) Criteria for Judging the Damage

Item	Symbol	Test Condition (T_c = 25 ºC)	Limit	
			Min.	Max.
Forward Voltage	V_F	I_F = 180 mA	L.S.L. * 0.9	U.S.L. * 1.1
Luminous Flux	Φ_v	I_F = 180 mA	L.S.L * 0.7	U.S.L * 1.3

6. Label Structure

a) Label Structure



Note: Denoted bin code and product code above is only an example (see description on page 5)

Bin Code:

ⓐⓑ: Forward Voltage bin (refer to page 11)

ⓒⓓ: Chromaticity bin (refer to page 9-10)

ⓔⓕ: Luminous Flux bin (refer to page 6)

b) Lot Number

The lot number is composed of the following characters:

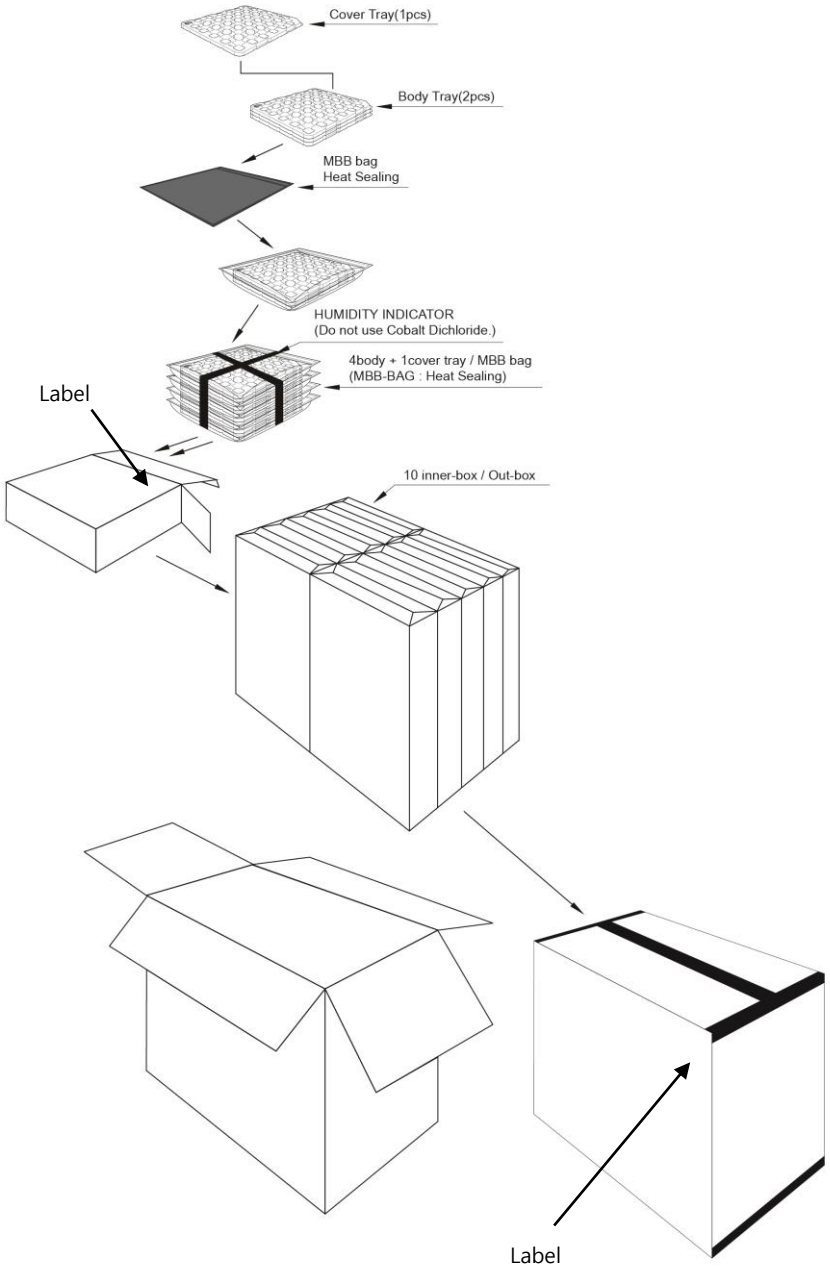
① ③④⑤⑥⑦⑧⑨ / 1ⓐⓑⓒ / xxxx pcs

①	:	Production site (S: Giheung, Korea, G: Tianjin, China)
②	:	4 (LED)
③	:	Product state (A: Normal, B: Bulk, C: First Production, R: Reproduction, S: Sample)
④	:	Year (Z: 2015, A: 2016, B: 2017…)
⑤	:	Month (1~9, A, B, C)
⑥⑦⑧⑨	:	Day (1~9, A, B~V)
ⓐⓑⓒ	:	Product serial number (001 ~ 999)

7. Packing Structure

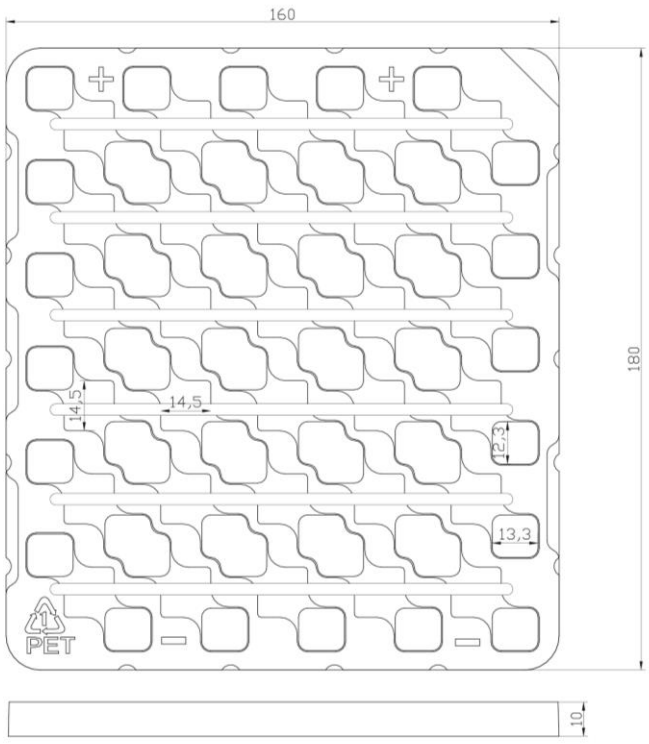
Packing material	Max. quantity in pcs of COB	Dimension(mm)			
		Length	Width	Height	Tolerance
Tray	30	160	180	10	1.0
Aluminum Bag	60(2 trays)	210	241		10
Inner Box	240	230	84	260	2
Outer Box	2400	476	445	272	5

a) Packing Structure

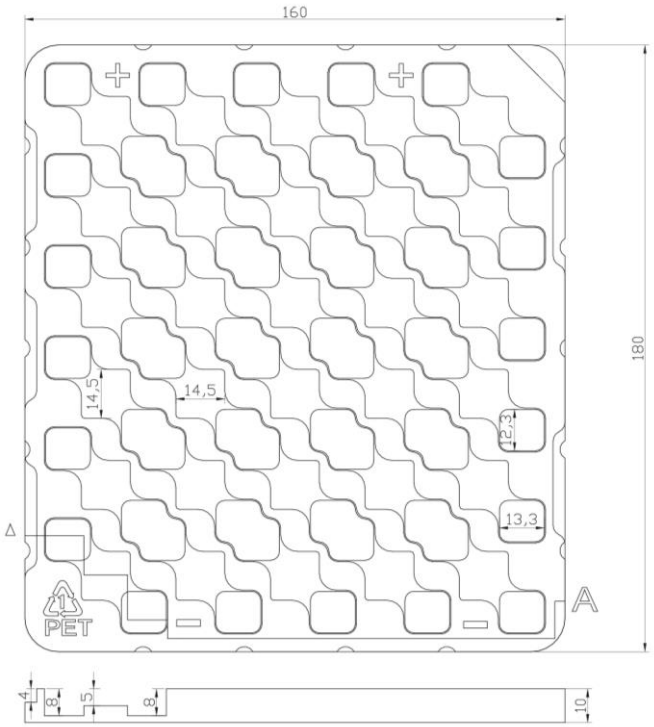


b) Tray

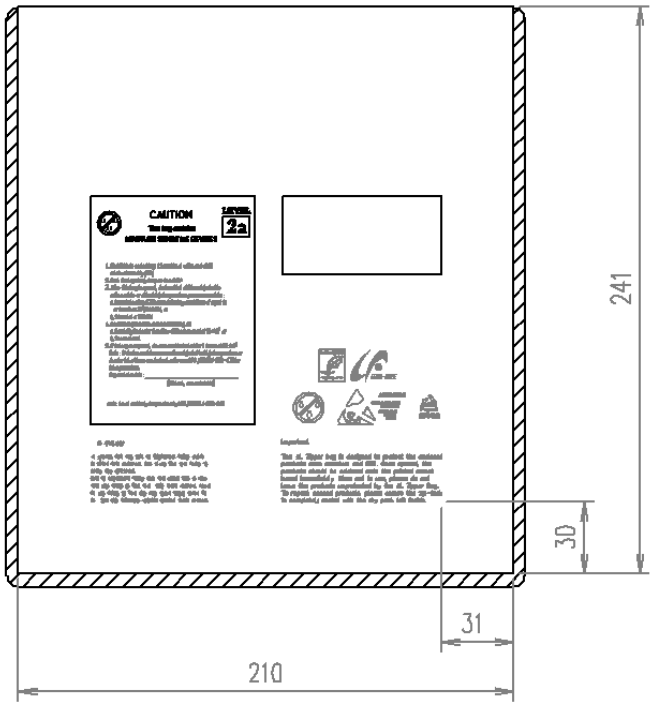
① Cover



② Body



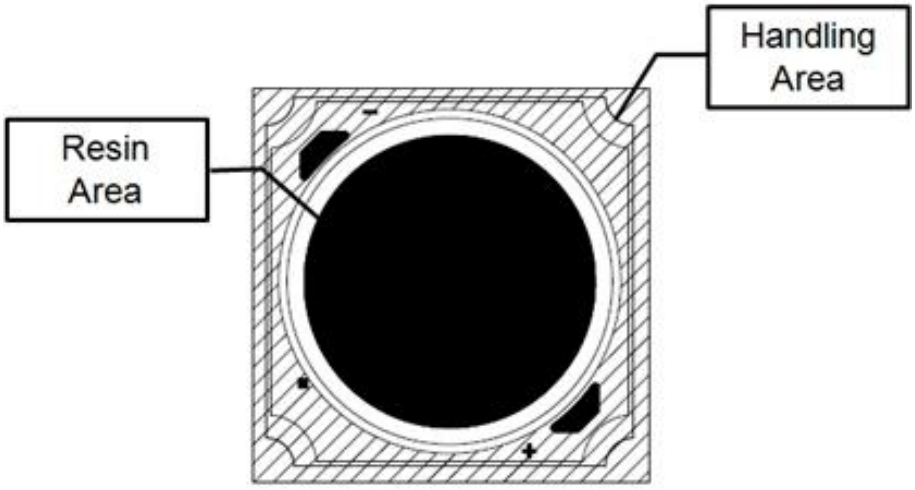
c) Aluminum Vinyl Packing Bag



8. Precautions in Handling & Use

1) This device should not be used in any type of fluid such as water, oil, organic solvent, etc. When cleaning is required, IPA is recommended as the cleaning agent. Some solvent-based cleaning agent may damage the silicone resins used in the device.
2) LEDs must be stored in a clean environment. If the LEDs are to be stored for three months or more after being shipped from Samsung, they should be packed with a nitrogen-filled container (shelf life of sealed bags is 12 months at temperature 0~40 ºC, 0~90 % RH).
3) After storage bag is opened, device subjected to soldering, solder reflow, or other high temperature processes must be:
   a. Mounted within 672 hours (28 days) at an assembly line with a condition of no more than 30 ºC / 60 % RH, or
   b. Stored at <10 % RH
4) Repack unused products with anti-moisture packing, fold to close any opening and then store in a dry place.
5) Devices require baking before mounting, if humidity card reading is >60 % at 23 ± 5 ºC.
6) Devices must be baked for 1 hour at 60 ± 5 ºC, if baking is required.
7) The LEDs are sensitive to the static electricity and surge current. It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs. If voltage exceeding the absolute maximum rating is applied to LEDs, it may cause damage or even destruction to LED devices. Damaged LEDs may show some unusual characteristics such as increase in leakage current, lowered turn-on voltage, or abnormal lighting of LEDs at low current.
8) The thermal management is one of the most critical factors for the LED lighting system. Especially the LED junction temperature should not exceed the absolute maximum rating while operation of LED lighting system.

   For more information, please refer to Application Note ‘Mechanical & Thermal Guide for COB’.
9) In case of driving LEDs around the minimum current level (If_min), chips might exhibit different brightness due to the variation in I-V characteristics of each one. This is normal and does not adversely affect the performance of product.
10) VOCs (Volatile Organic Compounds) can be generated from adhesives, flux, hardener or organic additives used in luminaires (fixtures). Transparent LED silicone encapsulant is permeable to those chemicals and they may lead to a discoloration of encapsulant when they exposed to heat or light. This phenomenon can cause a significant loss of light emitted (output) from the luminaires. In order to prevent these problems, we recommend users to know the physical properties of materials used in luminaires and they must be carefully selected.
11) The resin area is very sensitive, please do not handle, press, touch, rub, clean, or pick by with tweezers on it. Instead, please pick at the handling area as indicated below.



Legal and additional information.

About Samsung Electronics Co., Ltd.

Samsung Electronics Co., Ltd. inspires the world and shapes the future with transformative ideas and technologies, redefining the worlds of TVs, smartphones, wearable devices, tablets, cameras, digital appliances, printers, medical equipment, network systems and semiconductors. We are also leading in the Internet of Things space through, among others, our Digital Health and Smart Home initiatives. We employ 307,000 people across 84 countries. To discover more, please visit our official website at www.samsung.com and our official blog at global.samsungtomorrow.com.

Samsung Electronics Co., Ltd.
95, Samsung 2-ro
Giheung-gu
Yongin-si, Gyeonggi-do, 446-711
KOREA

www.samsungled.com

SAMSUNG